

Document	Datasheet
Туре	Dielectric Chip Antenna
Application	2.4 GHz
Part No.	AMAN1503030ST01
Revision	0

# DATASHEET



# Application

Bluetooth Zigbee WLAN (IEEE 802.11 b/g) ISM 2.4GHz Wireless Devices

#### **Features**

PIFA structure Size (15\*3\*3mm<sup>3</sup>) **Optimized for on-ground condition** SMT available under Pb-free condition RoHS compliant

Automotive applications qualified (AEC-Q200)

# AMOTECH

Notes

The contents of this datasheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.



# **Revision History**

Rev. No	Date	Title	Contents	Page
	'23.10.10		Preliminary published	

## Table of Content

1. Specifications	3
1.1 Electrical Specifications	
1.2 Mechanical Specifications	
1.3 Appearance and Material	
2. PCB Design for Test	
2.1 Evaluation Board Dimension	
2.2 PCB Design Guide	
3. Measurement Result	5
3.1 Typical Measurement Result (VSWR)	
3.2 Typical Measurement Result (Gain, Radiation Pattern)	
4. Reliability	8
5. Cautions (Recommendations)	9
6. Soldering Reflow Profile	9
7. Packaging	10
7.1 Carrier Tape Dimension	
7.2 Packaging Quantity	
7.3 Packaging Label	



# 1. Specifications

1.1 Electrical Specifications

No	Item	Specification	Remark
1	Frequency Range [GHz]	2.4 ~ 2.485	
0		Max 2 : 1	Non-GND
2	VSVVR	Max 3 : 1	On-GND
3	Total Avg. Gain [dBi]	Тур1.20	
4	Efficiency [%]	Тур. 75	
5	Polarization	Linear	
6	Impedance [Ω]	Nominal 50	

 $\checkmark$  The results are measured on the 70 x 50mm² evaluation board(EVB).

✓ See Page 6. for more detail gain parameter

#### 1.2 Mechanical Specifications

No	ltem	Spec.	Remark
1	Dimensions [L * W * H]	15.0 * 3.0 * 3.0 mm <sup>3</sup>	
2	Unit Weight	typ. 0.45 g	
3	Operating Temperature	-40 ~ +125 ℃	

#### 1.3 Appearance & Material

No	Item	Function	Material
1	Marking	Feeding Index	Ink
2	Marking	P/N & Week number	Ink
3	Ceramic Body	-	Ceramic



Side view

3 ±0.15

3 ±0.15



## 2. PCB Design for Test



2.2 PCB Design Guide





#### 3. Measurement Result

3.1 Typical Measurement Result (VSWR)



No	Matching Value		
No Non-GND		On-GND	
[1]	0 ohm	0 ohm	
[2]	N/C	N/C	
[3]	100 pF	100 pF	
[4]	N/C	1.5 pF	



#### Measured VSWR with Non-GND condition



Measured VSWR with On-GND condition

 $\checkmark$  The results are measured on the 70 x 50mm² evaluation board (EVB).



3.2 Typical Measurement Result of Non-GND type (Gain, Radiation Pattern)

Frequency [MHz]	Peak Gain [dBi]	Avg. Gain [dBi]	Efficiency [%]
2400	73.74	-1.32	2.09
2442	80.73	-0.93	2.32
2485	75.48	-1.22	2.29





[Azimuth plane @2.442GHz ]



[Elevation1 plane @2.442GHz ]





3.3 Typical Measurement Result of On-GND type (Gain, Radiation Pattern)

Frequency [MHz]	Peak Gain [dBi]	Avg. Gain [dBi]	Efficiency [%]
2400	55.43	-2.56	1.46
2442	69.58	-1.58	2.80
2485	58.58	-2.32	1.63





[Azimuth plane @2.442GHz ]



[Elevation1 plane @2.442GHz ]





# 4. Reliability

No	Item	Test Condition	Test Requirements
1	Adhesive Strength of Termination	<ol> <li>Applied force on SMT chip till detached point from PCB.</li> <li>F</li> <li>PCB</li> </ol>	<ol> <li>No mechanical damage by applied force</li> <li>Strength (F) &gt; 5 kgf</li> </ol>
2	Temperature Cycling	1. Step 1 : -40 ± 3℃, 30 min Step 2 : +125 ± 3℃, 30 min 2. Number of cycle : 30	1. No visual damage 2. Within electric spec (VSWR)
3	High Temperature Resistance	1. Temperature : +125 ± 5 ℃ 2. Time : 1000 ± 24 hrs	1. No visual damage 2. Within electric spec (VSWR)
4	Humidity	1. Humidity : 85 % RH Temperature : +85 ± 3℃ 2. Time : 1000 ± 24 hrs	1. No visual damage 2. Within electric spec (VSWR)
5	Vibration	1. 10-2000 Hz, Amp 1.5 mm, 5 g, 20 min 2. 12 cycles each of 3 orientations	1. No visual damage 2. Within electric spec (VSWR)
6	Resistance to Solvents	1. Dipping glass cleaner 2. 2 hrs	1. Cracks, peeling, and damage should not occur
7	Resistance to Soldering Heat	1. Reflow simulation 260 ℃ 2. 10 sec	1. No visual damage 2. Within electric spec (VSWR)
8	Solderability	1. Dipping 245±5 ℃ 2. 5 sec	1. More than 95% lead on SMT area
9	Board Flex	1. 2mm, 60 sec	1. Cracks should not occur
10	ESD	1. 8 KV, Contact discharge 2. 100 times	1. No visual damage 2. Within electric spec (VSWR)
11	Mechanical Shock	1. 100 g, 6 ms 2. 3 times each of orientations	1. No visual damage 2. Within electric spec (VSWR)

% Reliability test items and conditions are subject to change by customer request.



# 5. Cautions (Recommendations )

- ✓ Storage environment of parts must be at ambient temperatures of 5 to 40°C and maximum 60%RH humidity
- ✓ The parts should be used within 6 months from the time of delivery. If stored for over 6 months, check for solder ability before use.

#### 6. Soldering Reflow Profile





## 7. Packaging

7.1 Carrier Tape Dimension



Item	Spec.	ltem	Spec.	ltem	Spec.
A0	3.30 ±0.10	P0	4.00 ±0.10	E	1.75 ±0.10
BO	15.30 ±0.10	P1	8.00 ±0.10	F	11.50 ±0.10
К0	3.30 ±0.10	P2	2.00 ±0.10	W	24.00 ±0.30
D0	1.50 -0.00 / +0.10	10*P0	10*P0 ±0.20	Т	0.30 ±0.10

#### 7.2 Packaging Quantity

ltem	Quantity	Dimension
Reel	1,000 ea	Ф13″ * 24mm
Inner	1,000 ea (1 Reel)	350 * 350 * 90 (mm3)
Outer Box	3,000 ea (3 Inner Box)	390 * 390 * 280 (mm3)

#### 7.3 Packaging Label

